



#### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C
00) (	150mΩ @ V <sub>GS</sub> = -4.5V	-1.9A
-20V	200mΩ @ V <sub>GS</sub> = -2.5V	-1.7A

#### Description

This MOSFET is designed to minimize the on-state resistance  $(R_{DS(on)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

# Applications

- Backlighting
- Power Management Functions
- DC-DC Converters
- Motor Control

#### Features

- Very Low On-Resistance
- Very Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)

P-CHANNEL ENHANCEMENT MODE MOSFET

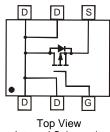
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

## **Mechanical Data**

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
  Solderable per MIL-STD-202, Method 208 3
- Weight: 0.006 grams (Approximate)



Top View



Internal Schematic

### Ordering Information (Note 4)

Case	Packaging
SOT-563	3000/Tape & Reel

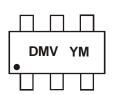
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



DMV = Marking Code YM = Date Code MarkingY = Year (ex: T = 2006)

M = Month (ex: 9 = September)

Year	2006	2007		2014	201	5 2	2016	2017	201	8	2019	2020	2021
Code	Т	U		В	С		D	E	F		G	Н	I
Month	Jan	Feb	Mar	Apr	Мау	Jun	J	u A	ıg	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	7	3	9	0	N	D
DMP2104\/						1 of 6						Septe	mber 2014



## Maximum Ratings (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V <sub>DSS</sub>	-20	V		
Gate-Source Voltage	V <sub>GSS</sub>	±12	V		
Continuous Drain Current (Note 5) $V_{GS} = -4.5V$	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	-1.9 -1.5	А
Continuous Drain Current (Note 5) $V_{GS}$ = -4.5V		T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	-2.1 -1.65	А
Continuous Drain Current (Note 5) $V_{GS}$ = -2.5V		T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	-1.7 -1.3	A
Pulsed Drain Current	t <sub>p</sub> :	= 10µs	I <sub>DM</sub>	-4.0	А

# **Thermal Characteristics**

Characteristic	Symbol	Value	Units
Power Dissipation (Note 5)	PD	0.85	W
Thermal Resistance, Junction to Ambient $@T_A = +25^{\circ}C$ (Note 5)	R <sub>0JA</sub>	146	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

# Electrical Characteristics (@T<sub>A</sub> = +25°C unless otherwise specified.)

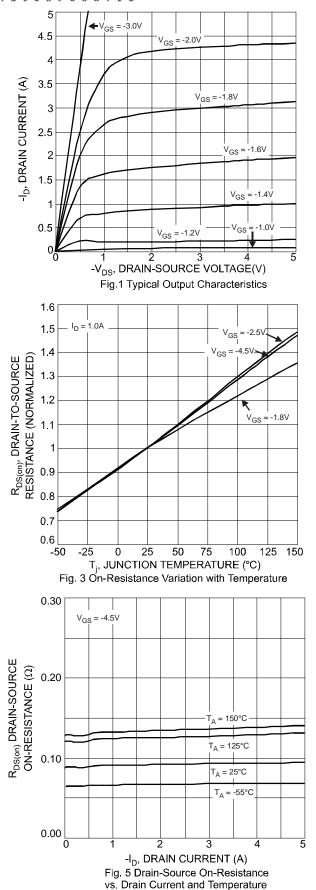
Characteristic			Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						·	
Drain-Source Breakdown Voltage			-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current $T_J = +25^{\circ}C$ $T_J = +125^{\circ}C$		I <sub>DSS</sub>	_	_	-1.0 -5.0	μA	$V_{DS}$ = -20V, $V_{GS}$ = 0V
Gate-Source Leakage		IGSS	_		±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage		V <sub>GS(th)</sub>	-0.45		-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
Static Drain-Source On-Resistance		R <sub>DS (ON)</sub>	_	92 134 180	150 200 240	mΩ	$\label{eq:VGS} \begin{array}{l} V_{GS} = -4.5V, \ I_D = -950mA \\ \hline V_{GS} = -2.5V, \ I_D = -670mA \\ \hline V_{GS} = -1.8V, \ I_D = -200mA \end{array}$
Forward Transconductance		<b>g</b> fs	_	3.1		S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -810mA
Diode Forward Voltage (Note 6)		V <sub>SD</sub>	_		-0.9	V	$V_{GS} = 0V, I_{S} = -360mA$
DYNAMIC CHARACTERISTICS							
Input Capacitance		Ciss	_	320		pF	
Output Capacitance		Coss	_	80		pF	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V f = 1.0MHz
Reverse Transfer Capacitance		C <sub>rss</sub>	_	60		pF	

Notes:

Device mounted on FR-4 PCB with 1 inch square pads.
 Short duration pulse test used to minimize self-heating effect.

# DMP2104V





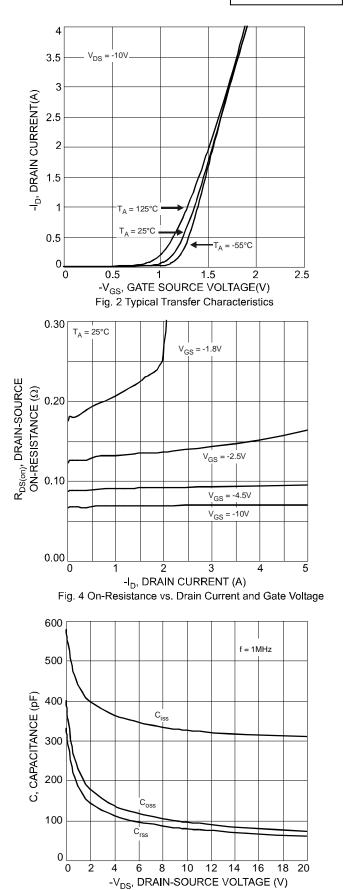
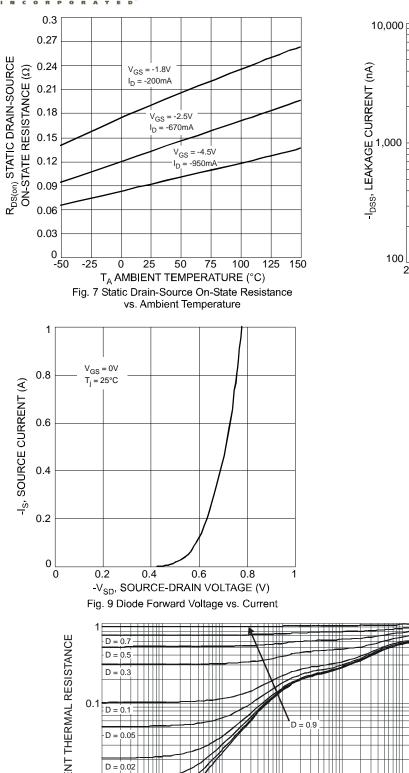
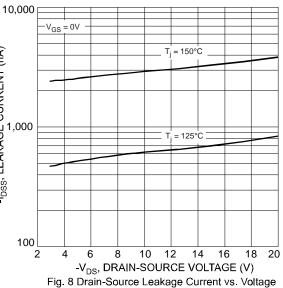


Fig. 6 Typical Capacitance

DMP2104V Document number: DS30942 Rev. 8 - 2





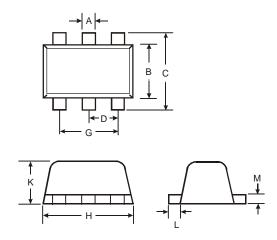


r(t), TRANSIENT THERMAL RESISTANCE  $\begin{aligned} \mathsf{R}_{\theta \mathsf{J}\mathsf{A}}(t) &= \mathsf{r}(t) * \mathsf{R}_{\theta \mathsf{J}\mathsf{A}} \\ \mathsf{R}_{\theta \mathsf{J}\mathsf{A}} &= 146^{\circ}\mathsf{C}/\mathsf{W} \end{aligned}$ 0.01 D = 0.01 P(nk) D = 0.005 t<sub>2</sub>  $T_J - T_A = P * R_{\theta JA}(t)$ Duty Cycle,  $D = t_1/t_2$ D = Single Pulse 0.001 0.00001 0.0001 0.001 100 1,000 0.01 0.1 10 t<sub>1</sub>, PULSE DURATION TIME (s) Fig. 10 Transient Thermal Response



# **Package Outline Dimensions**

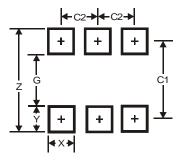
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT-563							
Dim	Min	Тур					
Α	0.15	0.30	0.20				
В	1.10	1.25	1.20				
С	1.55	1.70	1.60				
D	-	-	0.50				
G	0.90	1.10	1.00				
Н	1.50	1.70	1.60				
κ	0.55	0.60	0.60				
L	0.10	0.30	0.20				
М	0.10	0.18	0.11				
All Dimensions in mm							

# Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5



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